

2A, 200V-1000V High Efficient Surface Mount Rectifiers

FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- Low power loss, high efficiency
- Fast switching for high efficiency
- Low profile package
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Freewheeling application
- Switching mode converters and inverters, computer and telecommunication.

MECHANICAL DATA

- Case: SOD-128
- Molding compound meets UL 94V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Pure tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.028 g (approximately)



SOD-128

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$I_{F(AV)}$	2	A
V_{RRM}	200 - 1000	V
I_{FSM}	60	A
$T_{J\ MAX}$	150	°C
Package	SOD-128	
Configuration	Single Die	

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	HS2DFS	HS2GFS	HS2JFS	HS2KFS	HS2MFS	UNIT
Marking code on the device			HS2DFS	HS2GFS	HS2JFS	HS2KFS	HS2MFS	
Repetitive peak reverse voltage		V _{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value		V _{R(RMS)}	140	280	420	560	700	V
Forward current		I _{F(AV)}	2					A
Surge peak forward current, single half sine-wave superimposed on rated load per diode	8.3ms at T _A = 25°C	I _{FSM}	60					A
	1.0ms at T _A = 25°C		120					A
Junction temperature		T _J	-55 to +150					°C
Storage temperature		T _{STG}	-55 to +150					°C

THERMAL PERFORMANCE

PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\theta JL}$	17	°C/W
Junction-to-ambient thermal resistance	$R_{\theta JA}$	53	°C/W
Junction-to-case thermal resistance	$R_{\theta JC}$	21	°C/W

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage per diode ⁽¹⁾	HS2DFS	I _F = 1.0A, T _J = 25°C	V _F	0.81	-	V
		I _F = 2.0A, T _J = 25°C		0.87	1.00	V
		I _F = 1.0A, T _J = 125°C		0.67	-	V
		I _F = 2.0A, T _J = 125°C		0.74	0.82	V
	HS2GFS	I _F = 1.0A, T _J = 25°C		0.90	-	V
		I _F = 2.0A, T _J = 25°C		0.99	1.30	V
		I _F = 1.0A, T _J = 125°C		0.76	-	V
		I _F = 2.0A, T _J = 125°C		0.86	0.96	V
	HS2JFS	I _F = 1.0A, T _J = 25°C		1.00	-	V
		I _F = 2.0A, T _J = 25°C		1.10	1.70	V
		I _F = 1.0A, T _J = 125°C		0.80	-	V
		I _F = 2.0A, T _J = 125°C		0.92	1.10	V
	HS2KFS HS2MFS	I _F = 1.0A, T _J = 25°C		1.30	-	V
		I _F = 2.0A, T _J = 25°C		1.48	1.70	V
		I _F = 1.0A, T _J = 125°C		0.94	-	V
		I _F = 2.0A, T _J = 125°C		1.11	1.23	V
Reverse current @ rated V _R per diode ⁽²⁾		T _J = 25°C	I _R	-	1	μA
		T _J = 125°C		-	80	μA
Reverse recovery time	HS2DFS HS2GFS	I _F =0.5A,I _R =1.0A, I _{rr} =0.25A	t _{rr}	-	50	ns
	HS2JFS HS2KFS HS2MFS			-	75	ns
Junction capacitance per diode	HS2DFS	1 MHz, V _R =4.0V	C _J	32	-	pF
	HS2GFS			25	-	pF
	HS2JFS			17	-	pF
	HS2KFS HS2MFS			12	-	pF

Notes:

(1) Pulse test with $PW = 0.3\text{ ms}$

(2) Pulse test with $PW = 30\text{ ms}$

ORDERING INFORMATION

ORDERING CODE⁽¹⁾	PACKAGE	PACKING
HS2xFS M3G	SOD-128	3,500 / 7" reel
HS2xFS M2G	SOD-128	14,000 / 13" reel

Notes:

(1) "x" defines voltage from 200V(HS2DFS) to 1000V(HS2MFS)

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

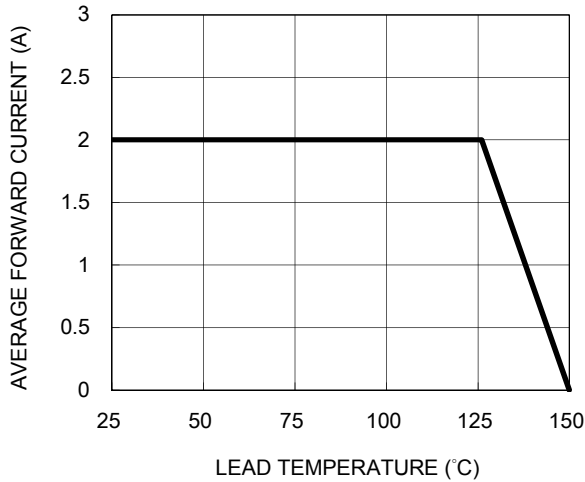


Fig.2 Typical Junction Capacitance

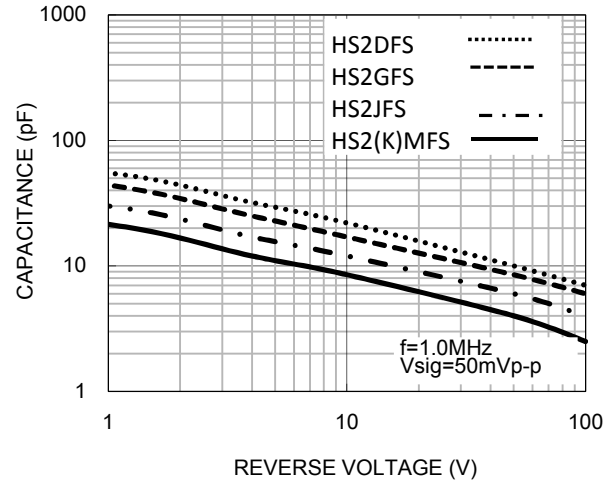


Fig.3 Typical Reverse Characteristics

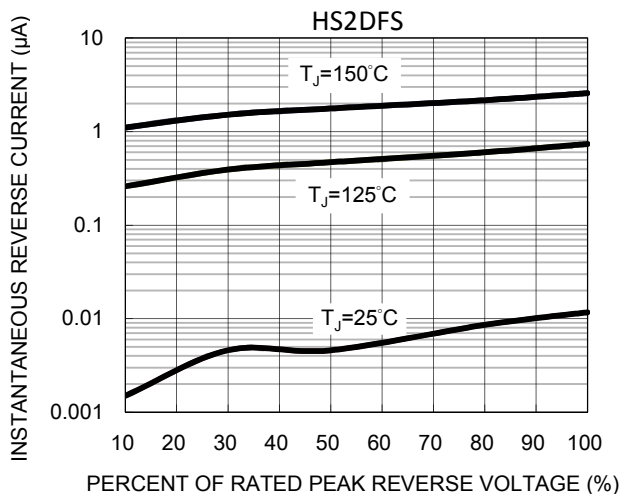


Fig.4 Typical Forward Characteristics

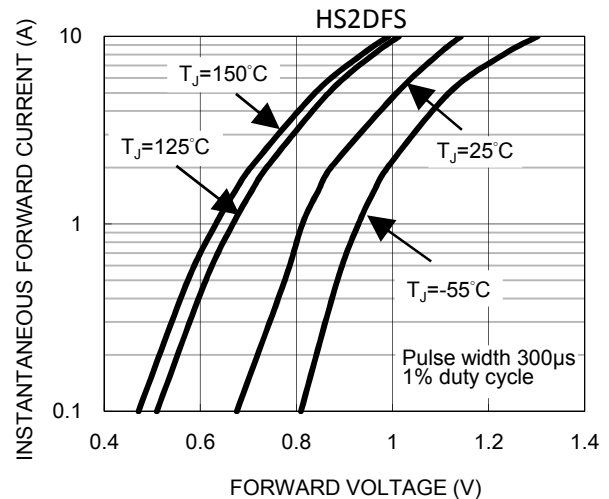


Fig.5 Typical Reverse Characteristics

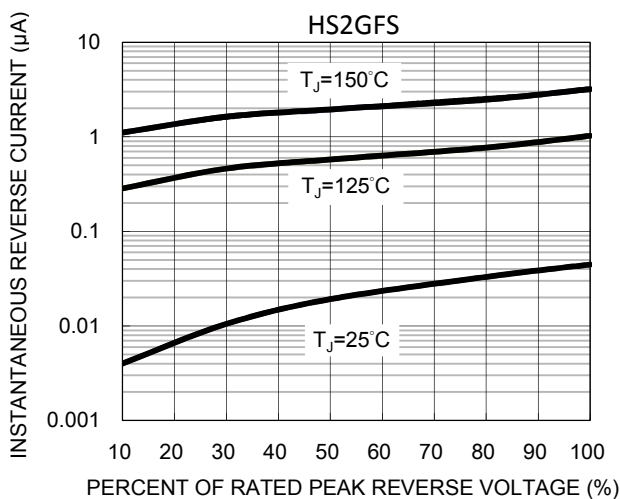


Fig.6 Typical Forward Characteristics

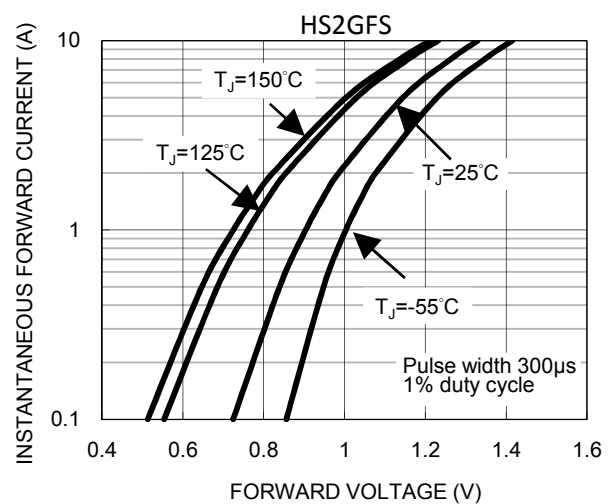


Fig.7 Typical Reverse Characteristics

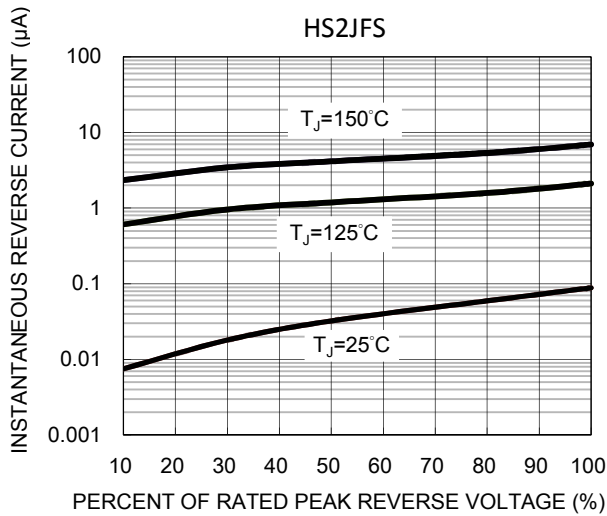


Fig.8 Typical Forward Characteristics

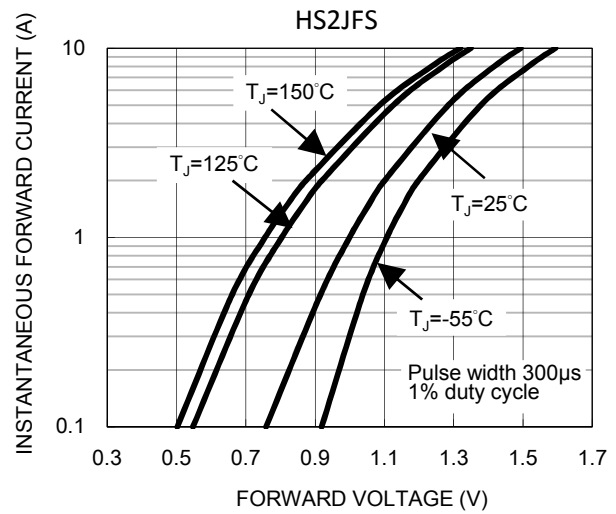


Fig.9 Typical Reverse Characteristics

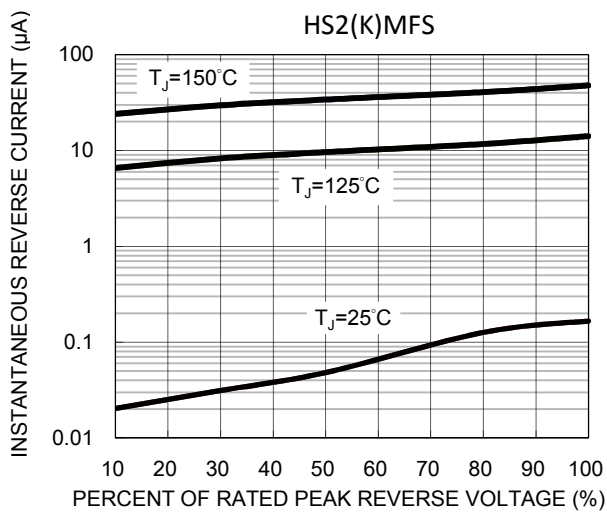


Fig.10 Typical Forward Characteristics

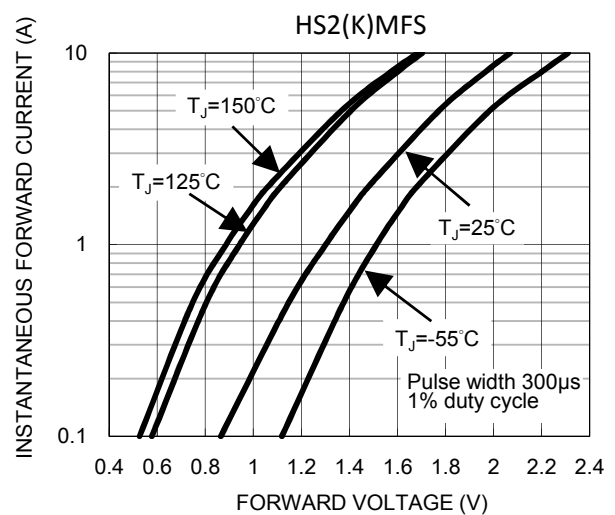
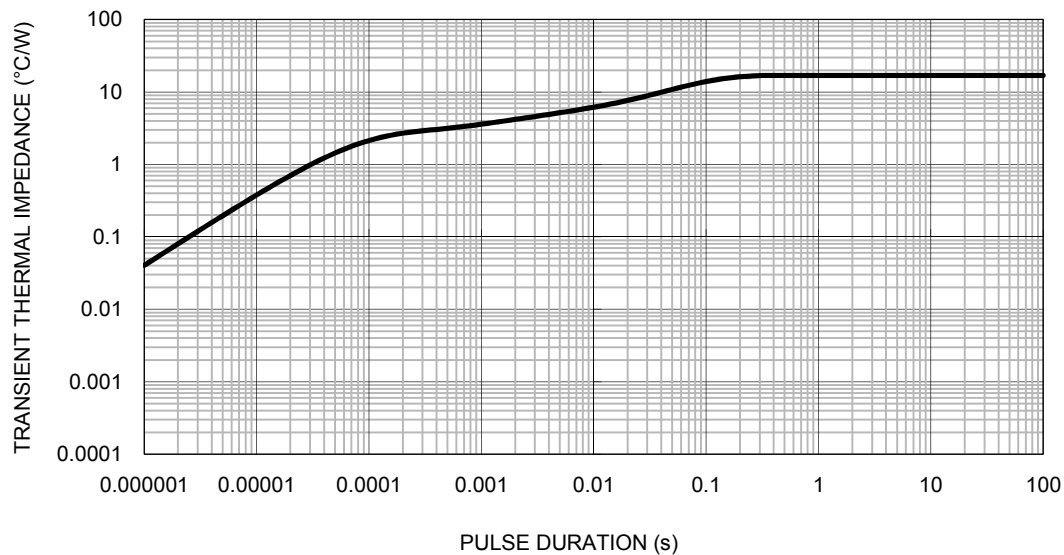
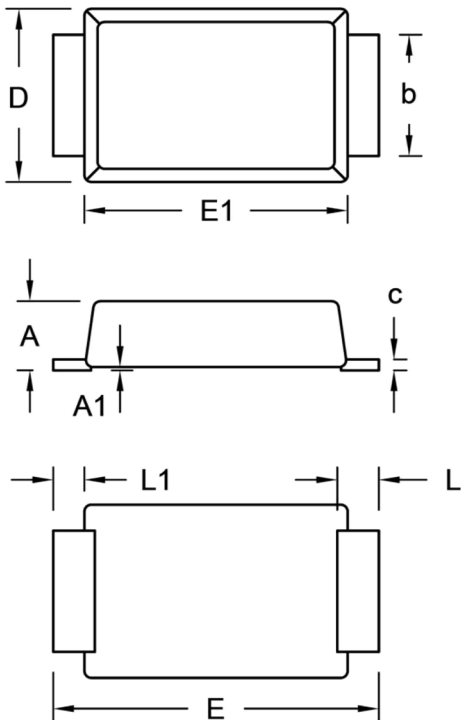


Fig.11 Typical Transient Thermal Impedance



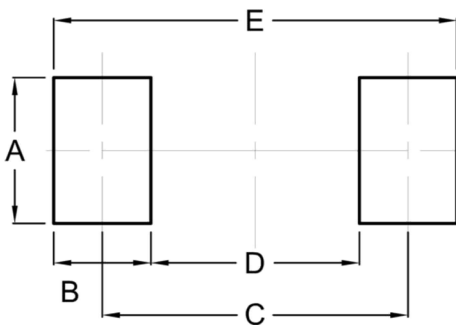
PACKAGE OUTLINE DIMENSIONS

SOD-128



DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	0.90	1.10	0.035	0.043
A1	0.00	0.10	0.000	0.004
b	1.60	1.90	0.063	0.075
c	0.10	0.22	0.004	0.009
D	2.30	2.70	0.091	0.106
E	4.40	5.00	0.173	0.197
E1	3.60	4.00	0.142	0.157
L	0.40	0.80	0.016	0.031
L1	0.30	0.60	0.012	0.024

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.10	0.083
B	1.40	0.055
C	4.40	0.173
D	3.00	0.118
E	5.80	0.228

MARKING DIAGRAM



P/N = Marking Code
 YW = Date Code
 F = Factory Code

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